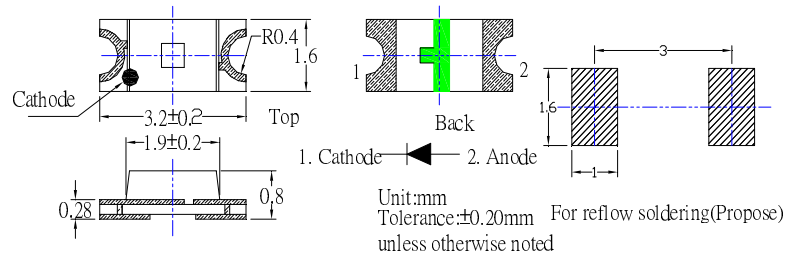


■Features

- Single chip
- Super high brightness of surface mount LED
- Compact package outline
(L x W x T) of 3.2mm x 1.6mm x 0.8mm
- Compatible to IR reflow soldering.

■Outline Dimension



■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

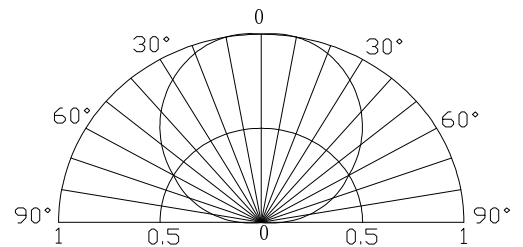
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value		Unit
		W5/M5/K5/B5/G5	G8/Y5/O5/R5	
DC Forward Current	I _F	30	30	mA
Pulse Forward Current*	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _D	108	78	mW
Operating Temperature	Topr	-40 ~ +85		°C
Storage Temperature	Tstg	-40~ +85		°C
Lead Soldering Temperature	Tsol	260°C/10sec		-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

Part Number	Color		V _F (V)			I _R (μA)	I _v (mcd)			λD (nm)			2θ1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			I _F =20mA			V _R =5V		I _F =20mA					
OSW51206C1E	White	W5	3.0	-	3.6	10	400	450	-	X=0.29 Y=0.29			120
OSM51206C1E	Warm White	M5	3.0	-	3.6	10	400	450	-	X:0.44, Y:0.41			120
OSK51206C1E	Pink	K5	3.0	-	3.6	10	60	90	-	X:0.38, Y:0.18			120
OSB51206C1E	Blue	B5	3.0	-	3.6	10	80	100	-	460	465	475	120
OSG51206C1E	True Green	G5	2.9	-	3.6	10	300	350	-	520	525	530	120
OSG81206C1E	Yellow Green	G8	1.8	-	2.6	10	20	45	-	565	570	575	120
OSY51206C1E	Yellow	Y5	1.8	-	2.6	10	60	90	-	585	590	595	120
OSO51206C1E	Orange	O5	1.8	-	2.6	10	100	120	-	600	605	610	120
OSR51206C1E	Red	R5	1.8	-	2.6	10	100	120	-	620	625	630	120

*1 Tolerance of measurements of chromaticity coordinate is ±10%

*2 Tolerance of measurements of dominant wavelength is ±1nm

*3 Tolerance of measurements of luminous intensity is ±15%

*4 Tolerance of measurements of forward voltage is ±0.1V

■ **Cautions:**

1. After open the package, the LED's floor life is 1 year under 30°C or less and 60%RH or less (MSL:2).
2. Heat generation must be taken into design consideration when using the LED.
3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
8. OPTOSUPPLY will not do 4M change without advance consultation.